



FORM PTO-1449 (REV. 7-80)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. NIT-288		SERIAL NO.	
LIST OF DOCUMENTS CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT N. KOFUJI et al			
				FILING DATE August 3, 2001		GROUP	
U.S. PATENT DOCUMENTS							
* EXAMINER INITIAL		DOCUMENT	DATE	NAME	CLASS	SUBCLASS	FILING DATE (If Appropriate)
	AA	6,232,237	5/15/01	Tamaoka et al			
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
							YES NO
	AL	11-176814	07/02/99	Japan			<input type="checkbox"/> <input type="checkbox"/>
	AM						<input type="checkbox"/> <input type="checkbox"/>
	AN						<input type="checkbox"/> <input type="checkbox"/>
	AO						<input type="checkbox"/> <input type="checkbox"/>
	AP						<input type="checkbox"/> <input type="checkbox"/>
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)							
	AR	TECHNICAL REPORT OF IEICE: "Technique for Forming Cu Dual Damascene Interconnect Using Low Dielectric Constant Films", S. Giho, August, 2000, pp. 87-92.					
	AS	GIJUTSU JOHO KYOKAI SHUPPAN, 12/27/00, "New Material and Process Technique of the Next Generation of ULSI Interconnect", pp. 295-305.					
	AT						
EXAMINER				DATE CONSIDERED			

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